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Tribological Properties of Fluorinated Amorphous Carbon Thin Films

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1. Introduction

1.1 Amorphous carbon characteristics
The peculiar electronic configuration of carbon atoms, $1s^2 2s^2 2p^2$, and the small energy difference between their 2p and 2s orbitals, compared to the binding energy of the carbon bonds, allow the electrons to rearrange in $s$ and $p$ mixed orbitals that enhance the binding energy with other atoms. This process is called hybridization and produces three different types of orbitals: $sp = s + p$, $sp^2 = s + p + p$ and $sp^3 = s + p + p + p$.

Each different bonding state corresponds to a certain structural arrangement: $sp$ bonding gives rise to chain structures (with two $\sigma$ bonds and two $\pi$ bonds), $sp^2$ bonding conforms onto planar structures (three $\sigma$ bonds and one $\pi$ bond) and finally $sp^3$ bonding produces tetrahedrical structures (four $\sigma$ bonds). The $p$ orbitals that form $\pi$ bonds overlap less than the orbitals forming $\sigma$ bonds. The reduced overlapping makes $\pi$ bonds weaker than $\sigma$ bonds. However, a number of scenarios are possible. Sometimes, as in ethene ($C_2H_4$), a $\sigma$ and $\pi$ bond combine producing a stronger bond between carbon atoms. This is called a double bond: $C\equiv C$. Triple bonds consist of a $\sigma$ bond and two $\pi$ bonds, as in ethyne ($C_2H_2$). Although chemically stronger thanks to double bonds, the mechanical stability obtained with $sp^2$ hybridization in solids is limited, due to the planar geometry. Instead, $sp^3$ hybridization allows the creation of a three dimensional network of $\sigma$ bonds.

Due to this variety of possible bonding configurations, carbon has a number of allotropes: graphene (sheet of $sp^2$ bonded carbons: $\sigma$ bonds plus delocalized $\pi$ bonds), carbon nanotubes and fullerenes (graphene sheets rolled over themselves forming cylinders or spheres, respectively), graphite (Bernal stack of graphene sheets), diamond (network of $sp^3$ bonded carbons) and amorphous carbon (cross-linked and non-organized carbon matrix with a mixture of $sp^2$ and $sp^3$ bonds). It is to the modification of the latter with fluoride that this chapter is devoted to.

The International Union of Pure an Applied Chemistry (IUPAC) defines amorphous carbon as “A carbon material without long-range crystalline order”. It also states that “Short range order exists, but with deviations of the interatomic distances and/or interbonding angles with respect to the graphite lattice as well as to the diamond lattice.”

Depending on the ratio of $sp^2$ and $sp^3$ bonds in the matrix, amorphous carbon (a-C) presents a variety of well-reviewed mechanical properties [Silva, 2003]. Tetrahedral amorphous carbon films (ta-C or TAC) present the highest hardness, with a high degree of $sp^3$ bonding and without hydrogen. It is almost exclusively deposited by filtered cathodic vacuum arc.
New Tribological Ways

(FCVA), [Martin et al., 1988; McKenzie et al., 1991; Fallon et al., 1993; Polo et al., 2000] although other techniques such as mass-selected ion beam (MSIB) [Kaukonen & Nieminen, 1992; Miyazawa et al., 1984] or laser deposition [Scheibe & Schultrich, 1994; Voevodin & Donley, 1996] can also be used. For the hydrogenated version of ta-C, plasma beam source (PBS) [Weiler et al., 1996] and electron cyclotron wave resonance (ECWR) [Morrison et al., 1999] have been used. Despite the high resemblance of ta-C to diamond on its short range microstructure and mechanical properties, its optoelectronics properties are controlled by the small percentage of sp² electrons with energies close to the Fermi level. [Silva, 2003]

On the other hand, films with comparable degrees of sp³ bonding but soft are named polymer like carbon (PLC). These films have high H content (above 40%), which terminates single bonds and therefore reduces carbon-carbon cross-linking. The quantity of sp³ bonds is high due to hydrogen’s preferential bonding to carbon in sp³ configuration, but this is no longer related to enhanced hardness. This kind of films present a small amount of defects compared to others and have a wide bandgap [Silva et al., 2002]. Films with intermediate hydrogen content can be either hydrogenated ta-C or hydrogenated a-C (a-C:H). The latter is the most studied type of a-C films and has been known in the literature as diamond-like carbon (DLC). It is softer than ta-C:H but still harder than most materials: values ranging from 20 to 40 GPa. Density is also slightly smaller than that of ta-C:H. Its main advantage is the simple setup for its deposition. A wide range of deposition techniques is available compared to the complex setup for ta-C deposition [Aisenberg & Chabot, 1971; Zou et al., 1989; Koidl et al., 1990; Kessels et al., 1998]. Also, DLC has a wider range of optical gaps than ta-C depending on the deposition conditions, which enables it for applications such as UV nanoimprint molds, where middle or near UV light transmission is necessary. For shorter wavelengths, thin films allow to further extend the working range.

Figure 1 shows the space of film types depending on the sp²:sp³ ratio and H content. Figure 1a is an updated version of the popular diagram by [Ferrari & Robertson, 2000] which includes hydrogenated films. Figure 1b by [Silva, 2003] presents a revised diagram based on a wider review.

![Fig. 1. Ternary diagrams of amorphous carbon types with respect to sp² and sp³ fraction, and H content. a) by [Robertson, 2002]; b) by [Silva, 2003].](www.intechopen.com)
High hardness and elastic modulus are the main features of a-C:H and ta-C(H) films. However, the rigid network of the films produces a high intrinsic compressive stress of up to 12 GPa [Ferrari et al., 2002]. This is an important drawback in the production of DLC coatings, since it limits the thickness depending on the adhesion to the substrate. For badly adhered or too thick films, cracks can appear and finally peel off the film if they progress, or otherwise dramatically reduce wear resistance. Thin buffer layers between substrate and film can be used to avoid this problem. Several transition metals and compounds can be used to this respect (W, Ta, TiC, Cr, SiC, etc.) depending on the substrate nature [Lee et al., 2000; Bahl et al., 2000; Kiuru et al., 2003].

With regard to surface properties, water contact angle has usually been examined providing relatively high values from 55° to 70°, depending on the presence of low energy C–H groups on the surface and the oxygen contamination of the film. The introduction of elements like F, Fe, Al and others has proven to be a useful method to increasing contact angle values up to more than 100° [Grischke et al., 1995; Chen et al., 2001].

1.2 Deposition methods

DLC can only be obtained at conditions far away from equilibrium, and so it is not spontaneously found in nature. The control of the growth parameters broadens the field of carbon microstructures and, in parallel, the properties of this material, which can only be synthesized in thin film form.

The production of a-C thin films is carried out by a large variety of deposition techniques. Some of them are adequate for laboratory studies while some others are more addressed to industrial production. Almost all processes work with low pressure of precursors or inert gases. Under these conditions, the increased mean free path of the species allows adequate particle energies, in order to obtain good mechanical and tribological properties. DLC films, and hard coatings in general, are very sensitive to particle bombardment during their growth. Therefore, this is a key parameter that must be controlled in any deposition method. Contamination by oxygen can affect importantly the properties of DLC. For this reason, clean processes in chambers capables of reaching low base pressures are used. The different methods to deposit DLC exhibit three characteristics [Silva, 2003]:

i. A plasma is used as the source of reactive species.

ii. The substrate is found, in general, at room temperature. At least there is no need to maintain a high substrate temperature during the process unlike in classical CVD processes.

iii. Energetic particles (ions and/or neutrals) participate in the deposition process.

**Ion beam deposition**

Ion beam deposition was the first method used for the synthesis of DLC [Aisenberg & Chabot, 1971]. Carbon and hydrocarbon ions coming from a graphite cathode are condensed in an energetic beam and produce sp³ states as they impinge on the growing film. Ion beam sources operate efficiently within an ion energy range of 100—1000 eV. Mass selected ion beam (MSIB) techniques are addressed to obtain ion beams with a certain energy. Ions pass through a magnetic filter that selects charged species with a fixed charge to mass ratio. Unfortunately, the ion beam is usually weakly ionized and, thus the mechanical properties of DLC are not optimal.

**Sputtering**

Magnetron sputtering is a well-known physical vapor deposition technique (PVD). It is one of the most used techniques, in industrial environments, to grow DLC. The impinging
species are commonly sputtered from a graphite target, which is RF- or DC-powered, in an Ar glow discharge [Rubio-Roy et al., 2007a]. The energy of the ion species being deposited can be increased or adjusted by applying a DC bias to the substrate or by using an unbalanced magnetron whose magnetic field substantially reaches the substrate. Reactive magnetron sputtering processes are also possible if hydrogen or hydrocarbon source gases are added to Ar. An alternative sputtering process can be performed without plasma: an Ar ion beam from an ion gun sputters a carbon target, say graphite, while another beam bombards the growing film to promote sp³ formation. This method is called ion beam assisted deposition (IBAD).

**Cathodic arc**

Cathodic arc constitutes one of the oldest vacuum deposition techniques [Randhawa, 1988; Sanders & Anders, 2000]. The arc discharge is concentrated at the cathode surface, where high ion densities (≈10¹² A/m²) form non-stationary spots. The ionization of species reaches 100% of the total flux, and the maximized parameter is the electron current to the anode, which is called arc current. The ion current is about 10−100 times lower than the arc current. This method is really appropriate to obtain hard DLC films, with a significant sp³ fraction, but certain issues have limited its use. First of all, films may present serious inhomogeneities due to the instabilities caused by the location of the arcs in the cathode. Secondly, the installation of a filtering device is necessary to prevent the deposition of macroparticles. Filtered cathodic vacuum arc (FCVA) solves the last problem by means of a magnetic filter, either in single bend or S-bend configuration [Robertson, 2002].

**Pulsed laser deposition**

Pulsed laser deposition (PLD) provides energetic ions, as in cathodic arc processes. Therefore, it is possible to deposit DLC films with high sp³ content with this technique, without the need of substrate biasing or great current discharges [Voevodin & Donley, 1996]. The intense energy pulses (15-30 ns) of a laser beam are able to vaporize a carbon target, which shows major advantages when it is graphite due to minimization of droplets emission. Fluxes of neutrals, ions and particulates are ejected from the target through an intense plasma, named plasma plume. The first PLD setups used Nd:YAG lasers, operating at a wavelength of 1064 nm. Nowadays, excimer lasers have progressively substituted them because higher-quality DLC is obtained using shorter wavelengths, for instance 193 nm and 248 nm (ArF and KrF lasers, respectively). The structures of DLC samples grown by PLD can be nanocrystalline diamond and ta-C.

**Plasma-enhanced chemical vapor deposition (PECVD)**

PECVD is a very popular technique to produce DLC films. A plasma is ignited in a reactor, between two electrodes of different areas, giving place to an asymmetrical discharge. The supplied power cannot be DC, since DLC may be electrically insulating. Thus, PECVD processes employ capacitively coupled RF power or pulsed-DC power. As depicted in figure 2, power is driven to the small electrode (cathode), where the substrate is placed, and the reactor walls are usually grounded (anode) [Rubio-Roy et al., 2007b]. The negative bias of the substrate cathode accelerates the bombarding ions to create sp³ sites. The enhancement of ion-to-neutrals ratio in the discharge needs low-pressure plasmas, but too low pressures will avoid a self-maintained discharge regime. This appropriate equilibrium is accomplished by raising the supplied power or by coupling an external magnetic field to the sheaths. The latter is performed in inductively coupled plasmas (ICP).
Electron cyclotron resonance systems (ECR) use both microwaves and magnetic field for a resonant transfer of energy to the electrons in the plasma. The simultaneous use of two different plasma sources, besides increasing the ionization degree, permits to decouple the particle flux and the bombarding energy of the ions [Corbella et al., 2008].

Fig. 2. Layout of a PECVD reactor.

**Electron cyclotron wave resonance (ECWR)**

When trying to couple low frequency electromagnetic radiation to a plasma, the latter behaves as a conductive medium and totally absorbs the incident waves within a characteristic absorption depth ("skin" depth). The plasma becomes transparent to the electromagnetic waves only when the excitation frequency exceeds the plasma frequency or when its conductivity is reduced (e.g.: with higher plasma density). However, RF excitation frequencies require very low plasma densities.

ECWR consists on applying a weak magnetic field (=20 G) that inhibits plasma conductivity by confining electrons in cyclotron orbits around the field lines. Hence, the electromagnetic radiation can be distributed across the plasma, which contributes to increase the plasma density and generates propagating electromagnetic modes [Morrison et al., 1999; Rodil, 2000]. The dimensions of the chamber are set so that one of these modes matches the resonant condition.

### 1.3 Tailoring of amorphous carbon properties

DLC shows special surface properties, and in some cases, they must be tuned depending on the selected application. The physical and chemical properties can be tailored by adding new elements into the a-C matrix as nanocomposites or by structuring the material in multilayers or gradient coatings. This provides the so-called modified a-C. Another strategy consists on patterning its surface, as explained in section 3.1.

Regarding the mechanical properties of DLC, both hardness and elastic modulus reach high values, and can be tailored by controlling the $sp^3$ fraction and hydrogen content, if any. Although hardness of a-C:H ranges from 20 to 40 GPa, the rigid network of the films provides an intrinsic compressive stress ranging from 0.5 to 12 GPa. This high stress is an important drawback in the production of DLC coatings, since it limits the film thickness to less than 1 μm. In fact, the accumulation of micro-strains within the amorphous matrix leads to a global compressive stress that is large enough to damage the film by development of cracks and strains that prevent the adhesion to substrates and reduce film stability. DLC
films, deposited by RF-PECVD, thicker than 50 nm are generally so stressed that they lose their consistency and delaminate. Besides improving adhesion to substrate, another strategy to avoid film peeling is stress relaxation. This is possible through doping with N, Si or metals, as well as by post-annealing or incorporation of nanometric particles (DLC nanocomposites), but these operations may degrade the mechanical properties [Zhang et al., 2002; Chen & Hong, 2003; Corbella et al., 2009a]. Metal incorporation in a DLC matrix has been proved to reduce stress below 1 GPa and maintain hardness and wear rate within acceptable values [Dimigen et al., 1987]. Low stress values are also achieved by depositing alternating hard and soft a-C layers [Ager et al., 1997; Logothetidis et al., 2000]. The resulting multilayered structures show a lower overall stress, and hardness is almost unaffected. Metal and a-C multilayers (Me/a-C) [Bertran et al., 2003], as well as a-CN/a-C structures [Pino et al., 2001], have been also deposited with similar results. Bias-graded deposition of DLC provides the best tribological performance through surfaces showing high $sp^3/sp^2$ ratios, which gradually decrease from the surface to the interface in order to enhance adhesion [Zhang et al., 2004]. Another way to improve coating adhesion consists in growing a buffer layer (Ti, Cr) prior to DLC deposition. Figure 3 summarizes the above mentioned strategies.

![Fig. 3. DLC modified structures: a) multilayers; b) buffer layers; c) composition-graded coatings; and d) nanocomposites.](image)

DLC films with hydrogen are mostly exploited in tribological applications due to their low friction coefficient and low wear rate. In all environments, the tribological behavior of DLC is controlled by an interfacial transfer layer formed during friction [Voevodin et al., 1996]. Thus, DLC is a valuable alternative as solid lubricant for applications where liquids are not convenient.

Besides wear and corrosion resistant, DLC is also known to be a hydrophobic material. The C–H groups located on the surface diminish the wettability, which is parametrized by the contact angle held between a liquid drop and the film surface. DLC typically exhibits a contact angle of 55–75° for water, although it can be increased by adding metals such as Fe or Al. In the case of Al-DLC, the contact angle exceeds 100° [Chen et al., 2001]. The high hydrophobicity shown by a-C:H:Si:O and a-C:H:F films is also advantageous for anti-sticking and self-cleaning applications [Grischke et al., 1998; Rubio-Roy et al., 2007b]. Highest values of contact angle are reached when combining hydrophobic films together with special surface architectures [Kim et al., 2007]. On the other hand, a-C:H:Si:O films find also applications as ophthalmic and decorative coatings due to their comparatively high optical transmittance. The resistance to higher temperatures makes a-C:H:Si ideal as protective coating in components for thermal processes.
Low roughness is another intrinsic surface property that makes DLC films suitable for certain tribological applications. DLC layers show a flat and smooth surface, with their roughness being minimized when deposited by filtered arc evaporation. RMS surface roughness below 0.05 nm has been reported for DLC deposited either by sputtering or PECVD [Peng et al., 2001]. These atomically flat surfaces show improved tribological properties of importance for applications such as hard drive disk coating. Moreover, surface roughness of ultra-thin DLC films is revealed to follow fractal scaling laws, i.e. it is related to film thickness through an exponential function [Casiraghi et al., 2004].

1.4 Applications
The wide variety of applications of DLC is mainly addressed to hard coatings with special tribological properties. These properties can be tuned by modifying DLC structure and by incorporating other elements [Hauert & Patscheider, 2000], whereas other properties ensure its performance as optical filter or for components with electronic functionality. The fastest growing market for DLC application during the previous years was the automotive industry [Lampe et al., 2003], in which DLC, ta-C, W-DLC and WC/C multilayers were being preferentially developed as hard and tribological coatings [Hauert, 2004]. Automotive industry demands solutions for preparing low friction and wear resistant coatings for lubricant performance on components. DLC fulfils these requirements and has been tested on a large number of automotive components: gears, wrist pins, valve filters and fuel injector parts. Specifically, serial production of metal-containing DLC (Me-DLC) coatings by physical vapor deposition has been performed on diesel injection systems [Gahlin et al., 2001]. The modern high-pressure injection systems were developed thanks to DLC. Also, racing cars were the first targets in automotive applications of DLC, where it was used to maximize engine power by friction reduction [Johnston & Hainsworth, 2005].

The combination of elevated hardness and wear resistance of DLC is appropriate for cutting and abrasive wear instruments, like drills and other machines used in material manufacturing. Optimal frictional properties of DLC coatings increase efficiency and lifetime of ultrasonic motors (USM), which have applications in robotics and automation equipments [Ko et al., 2005] where liquid lubricants are not an option. Also, dry lubricants are indispensable for pharmaceutical and food processing systems because of requirements of chemical inertness and low friction. In this way, any machine component is protected by DLC: worm gears, lead screws, roller bearings, compressors and air bearings. Concerning textile industry, the existence of residual substances and adding compounds in yarn motivate the coating with DLC of components of textile machines in contact with yarn, e.g. spinning rings, rapiers and needles. Anti-sticking properties of DLC are used to obtain better product quality in injection molding. Gillette Mach3 blade edges constitute a successful application of ta-C. These edges, coated by 150 nm thick DLC, appeared in 1998 and consolidated razor blades as one of the basic applications of this material.

DLC and modified DLC present elevated hydrophobicity, which is a basic requirement for surfaces of fluid-contacting components and devices. This material is useful to improve surface properties of inner walls of pipes and tubes. Presently, extensive research is being carried out to use DLC as gas barrier on the inside surfaces of bottles and packaging due to its high atomic density [Chhowalla, 2003; Abbas et al., 2005; Ozeki et al., 2009].
DLC coatings are applied in optical storage devices in order to protect the disk. The main conditions are low wear rate and transparency in the recording wavelength and low deposition temperature to allow the use of polymeric substrates. The high transparency in the infrared (IR) range makes DLC suitable for surface-protection applications in IR optics [Rusli et al., 2003]. In the visible range, sunglasses from Ray-Ban and glass plates for laser barcode scanner windows demonstrate the performance of DLC as scratch resistant coating for light transmitting surfaces [Hauert, 2004]. The control of interferential colors suggested DLC films for their use as decorative coatings. Electroluminescent and phase-shifting are other applications of DLC.

Protection to corrosion and wear of magnetic hard disks is one of the most widespread uses of ultra-thin DLC coatings [Morrison et al., 1999; Bhushan, 1999]. They must be ultra-thin to minimize the gap between the disk and the recording head, to achieve the highest areal storage densities. Magnetic media are currently protected by an approximately 2 nm thick DLC overcoat. Atomic smoothness (<0.15 nm) and absence of pinholes are of importance in order to protect the disk from corrosion [Jiang et al., 2010; Casiraghi et al., 2004].

Current research on DLC or modified DLC is mainly motivated by its biocompatibility [Grill, 2003; Hauert, 2004; Roy & Lee, 2007; Ma et al., 2007]. This property, together with antithrombogenicity, makes DLC-based films special candidates for medical applications where wear-resistant coatings, such as in prosthesis, are required. The surfaces of the implants are exposed to body cells and fluids, and are also exposed to potentially corrosive medium. These effects can provide cellular damage, infections, blood coagulation and failure of the implants. Coating the implants with protective films, which can reduce corrosion and wear, may extend the lifetime of implants by preventing or alleviating the aforementioned issues. Further biomedical applications include surgical tools and other devices in contact with blood or organic tissues [Dearnaley & Arps, 2005].

2. Modification with fluorine

2.1 Fluorine incorporation

In addition to metals, the introduction of Si, O, N or F in a-C films has also been investigated. In this case, O and N increase the surface free energy (SFE), while Si and F reduce it. Interestingly, addition of both Si and O can reduce the SFE more than only with Si [Grischke et al., 1995]. Among these elements, fluorine incorporation exhibits the highest water contact angles (higher than 100°) and the lowest surface energies (about 20 mJ/m²).

A number of recent studies regarding the introduction of F in DLC films (FDLC) can be found in the literature. However, one must distinguish between growing fluorinated films and fluorinating films or other surfaces. The former corresponds to the growth of films containing fluorine in bulk, while the latter only adds fluorine functionalization to the surface. This chapter focuses on the growth of fluorinated films.

Fluorination of surfaces is easily achieved by etching with common fluorocarbon plasmas. This consequence has sometimes been seen as an adverse effect and cleaning procedures have been designed to remove fluorinated groups from the surface [Simko et al., 1991]. Others have intentionally used fluorocarbon plasmas to functionalize surfaces [Miyamoto et al., 1991; Korotkov et al., 2007; Roy et al., 2007].

The advantage of growing fluorinated films is that even after being worn out to some extent, the new surface preserves bulk’s chemical composition. In addition, fluorine not only changes surface properties but also provides interesting bulk properties. Fluorinated
amorphous carbon has been extensively studied as a low dielectric constant (low-$\kappa$) material for electronic devices where parasitic capacitance must be avoided, because it can be deposited with microelectronic compatible methods. Static dielectric constant values as low as 2.1 have been obtained by RF-PECVD with CH$_4$ and CF$_4$, with increasing $\varepsilon_r$ with RF power [Endo & Tatsumi, 1995]. As a comparison, the traditional dielectric layer in microelectronics, SiO$_2$, has $\varepsilon_r = 4.0$ and current dielectrics used in 90 nm, 65 nm and 40 nm lines of Intel® processors have $\varepsilon_r = 3.0$ [Grill, 1999]. The other major property of fluorinated amorphous carbon is its reduced surface energy. Compared to Si, fluorine not only reduces its polar component but also the dispersive contribution. The introduction of fluorine in the film displaces hydrogen, and bigger -CF$_2$ and -CF$_3$ groups are formed. This reduces the network density therefore reducing the dispersive component [Grischke et al., 1995]. When the appropriate growing conditions are used, low surface energy coatings (20 mJ/m$^2$) with improved hardness (5 to 20 GPa) over PTFE (18 mJ/m$^2$ and 0.3 GPa) can be obtained. These conditions are reported to fall into the moderate fluorination conditions ($R_{\text{film}} = [\text{F}]/([\text{F}]+[\text{C}]) < 0.2$) [Donnet, 1998].

The deposition process of fluorinated a-C films is usually performed by PECVD although sputtering has also been used in some studies. The deposition by sputtering can be performed in reactive mode by using a graphite target and some fluorocarbon gas (e.g. CF$_4$, CHF$_3$, etc.) [Trippe et al., 2004; Jiang & Ning, 2006; Guerino et al., 2007] or by directly sputtering a PTFE target [Gonon & Sylvestre, 2002; Tang et al., 2005]. Instead, more work can be found in the literature about PECVD. There is a number of possible precursors with different C:F ratio which can be used to deposit fluorinated amorphous carbon. As reported, film’s fluorine content is primarily determined by the gas precursor chemistry. Generally, more fluorine in the process gas results in higher fluorine concentration in the film; adding hydrogen to the feed gas reduces the film F:C ratio [Mountsier & Samuels, 1998]. CF$_4$ is one of the highest F:C ratio precursors available. Combined with CH$_4$, it is reported to produce lower dielectric constant than other precursors, and Vicker’s hardness values from 5 to 10 GPa [Jacobsohn et al., 2000]. Other studies, show results for the same gases with hardness values from 16 to 19 GPa and surface free energy values descending from 40 mJ/m$^2$ for films deposited from pure CH$_4$ to about 28 mJ/m$^2$ for 4:1 CF$_4$:CH$_4$ gas flow ratio [Yu et al., 2003]. The results presented in this chapter were obtained using CHF$_3$, a barely studied gas for PECVD processes. Only a few papers, concerning deposition of low-$\kappa$ dielectrics, can be found in the literature and diamond-like properties have virtually not been sought with this precursor. Among them, an article from Winder and Gleason shows lower roughness values and higher fluorine incorporation for films deposited from CHF$_3$ than C$_2$H$_2$F$_4$ or CH$_4$F$_2$ [Winder & Gleason, 2000]. Xin et al. have also published work about growth of a-C:F:H films deposited with CHF$_3$ and using ECWR-PECVD. Neither the mechanical properties nor the surface energy of the films were examined [Xin et al., 2003].

However, more work can be found dealing with the use of CHF$_3$ as precursor for plasma treatments, including treatments of previously grown DLC films [Kawasaki et al., 2004]. Schwartzman and Wind make use of the modified DLC for NIL molds and show slightly lower surface free energy values for surfaces treated with CHF$_3$ than with C$_4$F$_8$ [Schwartzman & Wind, 2009].
2.2 Surface and chemical properties of FDLC

X-Ray Photoelectron Spectroscopy (XPS) [Goldstein et al., 1992] is an adequate technique to quantify fluorine to carbon ratio in the films, although it is not able to detect hydrogen. The analyzed films always show lower F to C ratio in the film than in the precursor. For example, for films deposited with pure CHF$_3$, F to C ratio in the gas is 3 while in the film is one. The results of F:C ratio in the film are shown in figure 4 as a function of $R_{\text{CHF}_3}^{\text{gas}} = \Phi_{\text{CHF}_3} / (\Phi_{\text{CHF}_3} + \Phi_{\text{CH}_4})$, where $\Phi_x$ represents the gas flow of x.

Fig. 4. Atomic F to C ratio in the film as determined from XPS analysis for two series of samples (deposited with 10 sccm of total gas flow, red squares; and 25 sccm blue circles).

The diamond-like characteristics of the films for low $R_{\text{CHF}_3}^{\text{gas}}$ suggest that the growth mechanism is ruled by the subplantation model [Robertson, 2002; Lifshitz et al., 1989, 1990, 1994]. Under these conditions, there is an intense energetic ion bombardment which subplants energetic species, either locally increasing stress (according to McKenzie et al. [McKenzie et al., 1991]) and stabilizing diamond-sp$^3$ phase, or by locally increasing density which would tend to increase sp$^3$ bonding as well (according to Robertson [Robertson, 1993]). In any case, ion bombardment causes the loss of hydrogen and fluorine from the surface and subsurface.

Ion bombardment is carried out by positively charged species that are accelerated in the plasma sheath towards the sample. At low $R_{\text{CHF}_3}^{\text{gas}}$, fluorine (and probably hydrogen) incorporation into the film is low while for low methane concentrations the F:C ratio rises significantly. The high hydrogen content provided by CH$_4$ probably etches away fluorine atoms back to the plasma, which fits with optical emission spectroscopic actinometry results, from the plasma, for atomic F. For a-C:H films, it is believed that atomic H, either neutral or ion, reacts with C–H bonds, abstracting H and creating H$_2$. According to these results, when fluorine is added, atomic H probably reacts with F in the film, as well, creating volatile HF.

As $R_{\text{CHF}_3}^{\text{gas}}$ is increased, hydrogen introduced as part of the feed gas is reduced and, eventually, fluorine content in the films starts to increase. Therefore, the reduction of atomic hydrogen increases the chances of fluorine to remain in the film. Fluorine, the substitute of
hydrogen when $R_{CHF}$ is increased, does not produce the same effect as H, due to its strong electronegativity, therefore avoiding the bombardment of F atoms. In addition, ion energy measurements have shown that the progressive substitution of CH$_4$ by CHF$_3$ reduces, and finally eliminates, the population of high energy ions [Corbella, 2009b]. The combination of hydrogen reduction, exchange by a strong electronegative atom (F) and reduction of the density of energetic ions bombarding the growing surface, would explain the non-linear increase of [F]/[C].

2.3 Friction of FDLC

Several factors influence the frictional behavior of DLC thin films: the degree of sp$^2$ or sp$^3$ carbon bonding, the amount of hydrogen in the film, the eventual alloying elements, the chemical and mechanical interactions between film and ball, the ball composition or the film and ball roughness [Erdemir & Donnet, 2006]. Moreover, the sliding conditions of speed and load [Heimberg et al., 2001] or debris production can also determine the possible interactions in the experiment. The interpretation of friction data is therefore not straightforward.

The results presented in this section correspond to measurements carried out with a nanotribometer (50 mN load) in a controlled N$_2$ + H$_2$O atmosphere as detailed elsewhere [Rubio-Roy, 2009]. Measurements show that friction coefficient is reduced for increasing relative humidity (RH) between 20% and 60%. Beyond that point, it does not suffer significant variation. Moreover, for high RH, friction does not seem to depend on the fluorination degree of the films. Regarding the effect of fluorine introduction, non-fluorinated films provide, on average, the lowest friction, while films deposited with $R_{CHF}^{gas} = 10\%$ show the highest friction (0.4 for 20\% RH). For higher F concentrations friction coefficient is reduced again. Low-fluorinated films see their friction more affected with humidity than non-fluorinated or highly-fluorinated DLC films.

Optical microscope photographs (see figure 5b) show fiber-like debris particles at both sides of the sliding track. This phenomenon occurs when discontinuous wear is given contrary to what happens when a transfer layer is present between the sliding counterpart and the film surface [Erdemir & Donnet, 2006]. Hydrogen terminated surfaces provide low friction characteristics due to the passivation of $\sigma$ and $\pi$ carbon bonds on the surface [Erdemir & Donnet, 2006]. As the WC ball slides over the surface, H atoms are mechanically removed from the film by strain effects thus leaving superficial dangling bonds [Li et al., 2005]. Depending on the experimental conditions, and specifically on the gas environment, hydrogen and hydroxyl groups originated from water will passivate these bonds again. In our experiment, for RH between 20\% and 60\% the results would justify this casuistic, so that bonds would react with water to restore themselves to a low energy state. However, for higher presence of water (from 60\% to 80\%), friction is stabilized for all films and independently of humidity or fluorine content (see figure 6). For these values of RH, a layer of physisorbed water could be formed on the surface, as already suggested by other authors [Erdemir & Donnet, 2006; Erdemir, 2001], which would make friction independent of the films’ variations.

Regarding the rather high friction values for $R_{CHF}^{gas} = 10\%$ in comparison to the rest, this behavior could be due to at least two competitive mechanisms. One of them would be the...
Fig. 5. a) Friction vs number of debris particles visible at 50× (200×200 µm). The dependence of friction with number of particles is only clear for high friction values; b) 50× optical microscope picture of a typical sliding track, corresponding to a film with \( R_{CHF_3}^{gas} = 10\% \) measured CHF$_3$ at 60% RH. Fiber-like debris particles are present at both sides of the sliding track.

Fig. 6. Friction dependence on humidity and fluorination degree.
somewhat beneficial effect of F presence to reduce friction by reducing adhesion to the sliding counterpart and by passivating carbon with a high-energy bond. The other would be the disadvantageous effect of a lower C atomic density (F is bigger than H), the reduced reservoir of H inside the film that would otherwise relink dangling bonds on the surface, and the probable decrease of H in the film as expected from the reduction in hydrogenated species in the plasma, from optical emission spectroscopic actinometry. The increase of friction with fluorine for humidity values below 40% is in agreement with other analogue works [Gilmore & Hauert, 2001].

The statistical analysis of 50× micrographs, taken after the tests, reveals that the influence of debris production in friction must also be taken into account as friction increases, where a stronger correlation between debris and friction is found. However, for low friction experiments, debris influence is limited and strongly coupled to microscopic effects (tests with similar debris production have different frictions and the other way round).

Films’ roughness (as measured from atomic force microscopy) is sufficiently low so that it is a minor factor in friction phenomena for the tested $R_{CHF}^{0.1}$ range, not producing interlocking and/or asperity-asperity interactions during sliding.

2.4 Abrasive wear of FDLC

Abrasive wear measurements were carried out with a 1:3 suspension of alumina particles 1 µm in diameter in glycerin. Such setup is highly hygroscopic and minimum changes in ambient humidity can affect the results. All measurements must be done during a short period of time (to avoid water absorption) and at a controlled temperature and relative humidity (here 23°C and 33%).

CSM Calowear equipment was used to measure the abrasive wear resistance of the amorphous carbon films. The measurement setup consists on a plastic or hardened stainless steel ball leaning against the surface of interest (which is tilted a known angle) and spun by a rotating shaft at a known distance from the surface. As the ball center does not move relatively to the surface, the footprint of the test is very small. More details about the setup can be found elsewhere [Gee et al., 2003].

Two different balls with equal diameter were used to test the wear resistance: a steel ball applying a force of 0.54 N and a plastic (polyacetal) ball producing 0.092 N of normal load. The deposited films showed high wear resistance up to $R_{CHF}^{0.8} = 80\%$ (see figure 7), with values in the range of $0.2 \times 10^3 \, \mu m^3/Nm$ to $0.4 \times 10^3 \, \mu m^3/Nm$, one order of magnitude more resistant than monocrystalline Si (100) in the same conditions ($2.1 \times 10^3 \, \mu m^3/Nm$). Fluorine content slightly increases wear rate, which is consistent with the observed changes in composition. The overall stability of the films is excellent. Data in figure 7 at $R_{CHF}^{0.8} = 10\%$, 40%, 60% and 80% correspond to two-year-old films, in contrast to the rest of data, which corresponds to recent (weeks old) films. Contact angle measurements also confirm the stability of the films. For more fluorinated films, this setup worn the film too much, so that the rate could not be measured. This is probably a consequence of both the reduced cohesive forces of the films and a loss of adhesion between film and buffer layer.

However, using the plastic ball during shorter periods of time, it could be determined that fluorinated films are up to 5 times more resistant than Si up to $R_{CHF}^{0.8} = 80\%$. Beyond that point, Si is more resistant, which evidences either a dramatic reduction of adhesion between film and buffer layer, or a strong structural and chemical change of the film.
3. Modification by surface structuring

3.1 Structuring strategies

Tribological measurements of patterned surfaces involve the use of macroscopic probes, in order to sufficiently average the effect of the structures. Therefore, large-area capable patterning techniques are required. Here, we report on the tribological properties of samples prepared by colloidal lithography (bottom-up approach), although other structures have also been prepared by electron beam lithography (top-down).

Colloidal lithography is a fast, cost-efficient technique able to produce periodic nanometric features in large-scale (up to some centimeters or more) with high quality. The technique consists on the arrangement of particles on a substrate so that they can be used as a template/mask for subsequent etching (see figure 8). Although CL is less versatile than EBL or other lithographic techniques, regarding non-periodic patterns, the reduction of time and resources for the production of large-area periodic nanopatterns represents important advantages for certain applications or fields such as photonic crystals, [López, 2003] thermophotovoltaics [Mao & Ye, 2010] or optical biosensors [Dorfner et al., 2009]. The differences in the structuring produced by ion beam etching with different angles have been studied as a method for nanoimprint mold fabrication [Portal et al., 2009].

On the other hand, the realization of sub-100 nm features in large areas with e-beam lithography (EBL) requires the stitching of several exposure fields. Proper alignment of the fields is complicated and, depending on how critical good stitching is, specific design of the equipment is required. Laser interferometer driven stages provide state-of-the-art stitching, but even with them a small thermal expansion/contraction of the sample after introduction on the e-beam writer is to be expected even for small temperature differences. This change in size can affect the stitching quality if enough time is not allowed for stabilization.

With these precautions taken into account, EBL is a suitable technique for large-area patterning, although expensive equipment is required, and patterning is slow. Other faster techniques such as those based on light (X-Ray or extreme UV lithography) can be much faster but also even more expensive.
In the following subsection we report on the friction and wear behavior of structured DLC films.

3.2 Friction and wear of patterned films

As described above, surface structuring leads to a variation in surface properties, such as adhesion, wear resistance, friction, wettability and gas adsorption. Textured coatings must show superior tribological properties in applications leading to strong interfacial interactions like nanoimprint molds, self-cleaning surfaces, MEMS and data storage devices. A series of DLC samples with modified surface topographies were prepared by colloidal lithography following the procedure schematized in figure 8. After DLC deposition on the patterned c-Si samples, the surface topography was studied by scanning electron microscopy (SEM) and atomic force microscopy (AFM), and friction tests were performed on them.

Coefficient of friction was measured by means of a nanotribometer from CSM Instruments in ball-on-disk configuration. The ST-117 cantilever was used with a WC ball 3 mm in diameter and 100 mN of load was applied on the sample, performing circular tracks of 1.6 mm in diameter at 1 mm/s during 6250 cycles. The measurements were carried out in a nitrogen atmosphere at 40% relative humidity, which was controlled by means of a PID system equipped with a water bubbler. More details can be found elsewhere [Rubio-Roy et al., 2009].

SEM micrographs in figure 9 show the surface morphology of DLC films deposited on substrates that underwent different times of ion beam etching. In these samples, film thickness is of the order of the pit depth after etching, i.e. 50 nm. The shadowing effect of the silica particles (SP) led to the formation of a pillar network. The substrate was only etched at the interstices of the 2-D crystal monolayer, which acted as a sacrificial template during the substrate lithography. Thus, the resulting topography reproduced the pattern of the CL template, where the pillar top coincides with the substrate region protected by the particle. In general, the pillar height increases with etching time. However, the surface structure
substantially changes when the etching time surpasses a threshold between 30 and 45 min. According to figure 9, the pillar network vanished with 45 min of substrate etching. At this etching time, the SP could not be removed from the patterned c-Si probably due to an effect of particle implantation. Furthermore, when the IBE is performed during 60 min, the SP are totally etched, i.e. the particle monolayer that constitutes the etching mask is removed by the bombarding ions and only the resulting rough surface remains.

Fig. 9. SEM micrographs of DLC-coated (50 nm) substrates patterned by colloidal lithography for different etching times: (a) 15, (b) 30, (c) 45 and (d) 60 min. [Corbella et al., 2010]

Figure 10a shows the evolution of coefficient of friction of a flat DLC film measured with the nanotribometer. This parameter increased gradually from 0.12 to 0.23 passing through different stages. As reported elsewhere, the curve is divided into three sections [Corbella et al., 2009b]: run-in period, transition regime and steady state. The variations in the first stage are ascribed to surface ploughing and mechanically induced desorption of hydrogen. During the transient regime, surface modification conformal to the ball shape takes place, as well as interactions with wear particles. Finally a steady state is achieved around cycle #4000. This scenario changes in the case of structured DLC samples (figures 10b and 10c). The coefficient of friction, which is already stabilized around or prior to cycle #1000, ranges between 0.17 and 0.20. The measured samples achieved lower and more stable values than in the flat DLC coating. Spikes in the friction coefficient (not shown in figure 10 due to data...
smoothing) could come from momentary interactions of the wear particles with the ball of the nanotribometer. These particles, which are debris removed from the sample during the tests, contribute to enhance the friction via several mechanisms, as for instance dragging, ploughing or adhesion.

Fig. 10. Evolution of coefficient of friction of DLC films deposited on a) flat, b) 15 min, and c) 30 min etched substrates. In the first plot, we have indicated the run-in period, transition region and steady state.

The wear effects on surface structure due to nanotribometry are evidenced by the morphological changes of the pillars located on the wear track. These pillars lost the concave ending observed in figure 9. Thus, the pillar edges constitute the initial contact region between the ball and sample surface. Since the pillars are progressively worn by the WC ball, the friction increases until the pillar top becomes flat. From this moment onwards, the coefficient of friction of the patterned DLC stabilizes into the values shown in figure 10. The wear rate was quantified from AFM profilometry of the volume removed by the ball. A value of $10^{-7}$ mm$^3$N$^{-1}$m$^{-1}$ was measured for flat DLC from the wear track left by the nanotribometer, whereas textured DLC exhibited a rate 10 times higher. The reduced contact area in the case of a patterned surface with respect to a flat surface may cause this
increase in wear rate. Therefore, more robust structures are required to improve the wear resistance.

The coefficient of friction of the sample etched during 15 min (figure 10b) is reduced 13% with respect to flat DLC, whereas the reduction corresponding to the sample etched for 30 min is 26% (figure 10c). This behavior is in agreement with the results from Jung et al., where the role of asperity size on friction was discussed [Jung et al., 2006]. The reduction in the stable values of coefficient of friction may be ascribed to the trapping effect of the pits defined by the micro-pillars. These interstices could store the wear particles generated during the tribological tests. The effect of these wear particles on friction force is thus alleviated in comparison with systems formed by lower pillars [Dumitru et al., 2003]. Also, the higher pillars lead to a weaker interaction with the sample due to the larger distance between the WC ball and the base surface. This explanation supports the monotonic reduction in friction coefficient as the pillar height increases. In this scenario, the preparation of a non-close-packed 2D crystal could give place to weaker friction forces due to a more important particle trapping. A more complete modeling of the tribological phenomena at the nanoscale should also account for the elastic response of the micro-pillars to the friction force.

4. References


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This book aims to recapitulate old information's available and brings new information's that are with the fashion research on an atomic and nanometric scale in various fields by introducing several mathematical models to measure some parameters characterizing metals like the hydrodynamic elasticity coefficient, hardness, lubricant viscosity, viscosity coefficient, tensile strength ... It uses new measurement techniques very developed and nondestructive. Its principal distinctions of the other books, that it brings practical manners to model and to optimize the cutting process using various parameters and different techniques, namely, using water of high-velocity stream, tool with different form and radius, the cutting temperature effect, that can be measured with sufficient accuracy not only at a research lab and also with a theoretical forecast. This book aspire to minimize and eliminate the losses resulting from surfaces friction and wear which leads to a greater machining efficiency and to a better execution, fewer breakdowns and a significant saving. A great part is devoted to lubrication, of which the goal is to find the famous techniques using solid and liquid lubricant films applied for giving super low friction coefficients and improving the lubricant properties on surfaces.

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